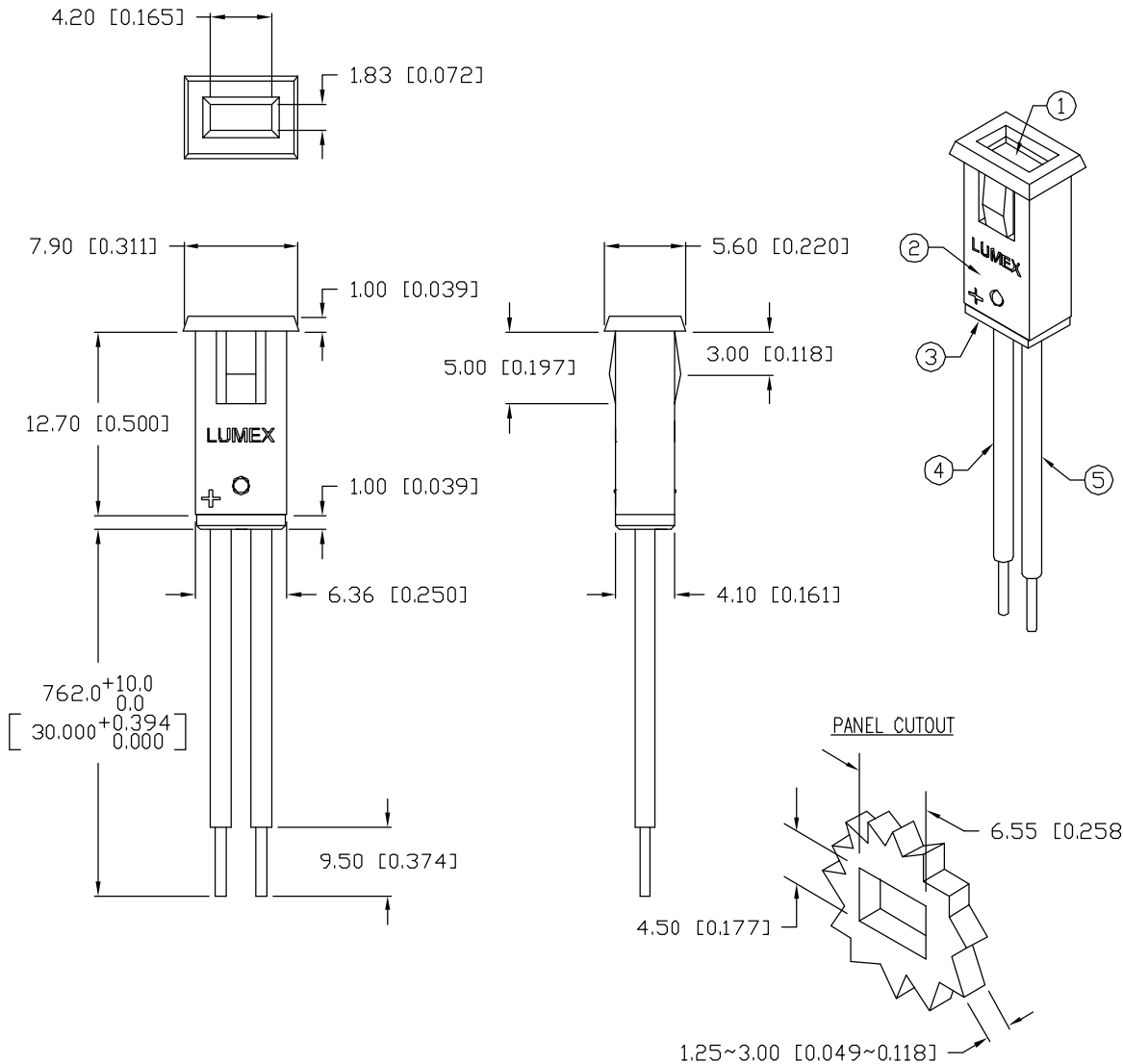


UNCONTROLLED DOCUMENT

PART NUMBER
SSI-LXMP059GD-760

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN IN 3D.	1.7.02



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		10		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		110		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

* $t < 10\mu\text{s}$

NOTES:

1. SSL-LX2573GD, GREEN LED. TRIM LEADS TO 3~4mm LONG.
2. SSH-LXMP059-HSG, BLACK HOLDER.
3. SSH-LXMP059-BSG2, BUSHING.
4. ANODE LEAD: LXP-WST24RDT0C, RED INSULATED, 24 AWG., CUT 767mm, STRIP 3mm & 9.5mm.
5. CATHODE LEAD: LXP-WST24BLT0C, BLACK INSULATED, 24 AWG., CUT 767mm, STRIP 3mm & 9.5mm.
6. CRIMP OR SOLDER LEAD WIRES TO LED AND ASSEMBLE INTO HOUSING.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION MAX= +0.00 -DECIMAL PRECISION

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565nm GREEN RECTANGULAR LED PANEL INDICATOR,
GREEN DIFFUSED LENS, 30" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 9.11.96
			PAGE: 1 OF 1
			SCALE: N/A